

**PRODUCT / PROCESS CHANGE INFORMATION**

**1. PCI basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCI No.</b>	MDG/19/11504	
<b>1.3 Title of PCI</b>	ST Shenzhen (China) additional source of Carrier Tape and Cover Tape for TSSOP 20 package products	
<b>1.4 Product Category</b>	All products in TSSOP20L from ST Shenzhen	
<b>1.5 Issue date</b>	2019-06-07	

**2. PCI Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	MARCELI SMIALKOWSKI
<b>2.1.2 Phone</b>	+44 1628896277
<b>2.1.3 Email</b>	marceli.smialkowski@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Ricardo Antonio DE SA EARP
<b>2.1.2 Marketing Manager</b>	Veronique BARLATIER
<b>2.1.3 Quality Manager</b>	Pascal NARCHE

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Wafer Fab (Consumables)	Packing: new supplier for customer deliveries	SH1T---ST SHENZHEN -CHINA

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	single source 3M carrier tape and 3M cover tape	first source 3M carrier Tape and 3M cover tape Second source CPAK carrier tape and CPAK cover tape
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	- Form: no change on the product, visual aspect change of the Carrier Tape and Cover Tape. - Fit: no change	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	To multiply the source to reduce line down risks.
<b>5.2 Customer Benefit</b>	LOGISTICS IMPROVEMENT

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	Not Applicable
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2019-05-29
<b>7.2 Intended start of delivery</b>	2019-05-29
<b>7.3 Qualification sample available?</b>	Not Applicable

**8. Qualification / Validation**

<b>8.1 Description</b>			
<b>8.2 Qualification report and qualification results</b>	In progress	<b>Issue Date</b>	

**9. Attachments (additional documentations)**

11504 Public product.pdf  
11504 PCi11504\_Additional information.pdf

10. Affected parts		
10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F030F4P6	

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## Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

**PCI Title :** ST Shenzhen (China) additional source of Carrier Tape and Cover Tape for TSSOP 20 package products

**PCI Reference :** MDG/19/11504

**Subject :** Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32F030F4P6	STM32F031F6P6	STM32F031F6P7
STM32F030F4P6TR	STM8S103F3P3TR	STM32F031F4P7
STM32F031F6P7TR	STM8S003F3P6	STM8S103F2P6
STM8S103F2P3	STM32F070F6P6	STM8S903F3P6TR
STM8S903F3P6	STM32F031F4P6TR	STM32F031F6P6TR
STM32F038F6P6TR	STM8L051F3P6	STM8S103F3P3
STM8S103F3P6TR	STM32F031F4P6	STM8S903F3P3
STM32F038F6P6	STM8S103F3P6	STM8S003F3P6TR
STM8S103F2P6TR	STM8SPLNB1P6	STM8S103F2P3TR



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